Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.					This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
	IPC Wab Site for Information on IPC 1752 Standard Form Type				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ous Materia	ials and Mfg Information				
Supplier Information															
Company name*	Company unique ID			1	Unique ID Authority					Response Date*					
onsemi												2023-06-08			
Contact Name	Title - Conta	Title - Contact			Phone - Contact*					Email - Contact*					
Product-Env-Stewards		Product Envi	Product Enviro Compliance			NA					Product-Env-Stewards@onsemi.com				
Authorized Representative*		Title - Representative			1	Phone - Representative*				Email - Representative*					
Product-Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
Requester Item Number	Requester Item Number Mfr Item		Number Mfr Item Name			Effective Date	Date Version Manufacturing Site		W	Veight*	UOM	Unit Type			
	LC82317	C823175PRA-4H Audio DSP for ca		navigation		2023-06-08		PHM		1	11.0	mg	Each		
Manufacturing Proccess In	nformation						,						·		
Terminal Plating / Grid	Terminal Plating / Grid Array Material T		erminal Base Alloy J-STD-02		Rating	Peak Process Body Tempera		Temperatu	ure Max Time at Peak Tempe		Temperatu	re Numb	per of Reflow Cyc	les	
SnAgCu	SnAgCu		CU Alloy 4			260		С	30		second	ls 3			
Comments															
or more information regarding	material composition	please refer to	page 3												

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	14.77	mg	Supplier	Silicon (Si)	7440-21-3		14.7183	mg
			Supplier	Polyimide	Proprietary Data		0.0517	mg
Die Attach	0.49	mg	Supplier	Fused Silica (SiO2)	60676-86-0		0.0049	mg
			Supplier	Acrylic resins	Proprietary Data		0.4704	mg
			В	Antimony Pentoxide (Sb2O5)	1314-60-9		0.0147	mg
Mold Compound-Black	46.71	mg		Epoxy resin	proprietary data		2.569	mg
			Supplier	Phenolic Resin	Proprietary Data		2.569	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1401	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		41.4318	mg
Solder Ball	24.88	mg	Supplier	Silver (Ag)	7440-22-4		0.7464	mg
			Supplier	Tin (Sn)	7440-31-5		24.0092	mg
			Supplier	Copper (Cu)	7440-50-8		0.1244	mg
Substrate and Solder Mask	23.81	mg	В	Nickel (Ni)	7440-02-0		1.0286	mg
			Supplier	Gold (Au)	7440-57-5		0.2095	mg
			Supplier	Bismaleimide Triazine resin	Proprietary Data		15.5003	mg
			Supplier	Copper (Cu)	7440-50-8		7.0716	mg
Wire Bond	0.34	mg	Supplier	Palladium (Pd)	7440-05-3		0.0034	mg
			Supplier	Gold (Au)	7440-57-5		0.3366	mg